

Amendments to the Claims:

The listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

Claims 1 - 8 (canceled)

Claim 9 (currently amended): A solder configuration, comprising a pad having a surface characterized as non-planar and circuitous and adapted to receive solder, thereby forming a portion of a solder joint, said non-planar and circuitous surface being disposed within an ~~upon which an intermetallic boundary interface is disposed, said intermetallic region encompassing boundary interface defining a separation between~~ said surface of said pad and said solder that forms part of a solder joint, said intermetallic boundary interface being characterized as non-planar and circuitous, whereby a crack forming in said solder proximate a boundary with said intermetallic region is influenced to proceed in a direction substantially parallel to said non-planar and circuitous surface along said interface with a non-planar, circuitous path, thereby lengthening its travel, and preventing failure of said solder joint.

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Claim 10 (currently amended): A solder configuration, comprising a pad having a surface characterized as a non-planar, serpentine surface adapted to receive solder, thereby forming a portion of a solder joint, said non-planar and serpentine surface being disposed within an ~~upon which an intermetallic boundary interface is disposed, said intermetallic region encompassing boundary interface defining a separation between~~ said surface of said pad and said solder that forms part of a solder joint, said intermetallic boundary interface being characterized as non-planar and serpentine, whereby a crack forming in said solder proximate a boundary

with said intermetallic region is influenced to proceed in a direction substantially parallel to said non-planar and serpentine surface along said interface with a non-planar, serpentine path, thereby lengthening its travel, and preventing failure of said solder joint.

Claim 11 (withdrawn): A solder configuration, comprising a pad having a surface upon which an intermetallic boundary interface is disposed, said intermetallic boundary interface defining a separation between said pad and solder that forms part of a solder joint, said intermetallic boundary interface being characterized as non-planar and having a plurality of steps, whereby a crack forming in said solder is influenced to proceed along said interface with a non-planar, stepped path, thereby lengthening its travel, and preventing failure of said solder joint.

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Claim 12 (withdrawn): A solder configuration, comprising a pad having a surface upon which an intermetallic boundary interface is disposed, said intermetallic boundary interface defining a separation between said pad and solder that forms part of a solder joint, said intermetallic boundary interface being characterized as non-planar and having a plurality of concentric interruptions, whereby a crack forming in said solder is influenced to proceed along said interface with a non-planar, interrupted path, thereby lengthening its travel, and preventing failure of said solder joint.

Claim 13 (withdrawn): A solder configuration, comprising a pad having a surface upon which an intermetallic boundary interface is disposed, said intermetallic boundary interface defining a separation between said pad and solder that forms part of a solder joint, said intermetallic boundary interface being characterized as non-planar and having a plurality of interdigitated interruptions, whereby a crack forming in said solder is influenced to proceed along said interface with a non-planar, interrupted path, thereby lengthening its travel, and preventing failure of said solder joint.

Appl. No. 10/038,264

Amdt. Dated October 8, 2003

Reply to Office action of October 2, 2003

Claim 14 (withdrawn): A solder configuration, comprising a pad having a surface upon which an intermetallic boundary interface is disposed, said intermetallic boundary interface defining a separation between said pad and solder that forms part of a solder joint, said intermetallic boundary interface being characterized as non-planar and having a cross-shaped interruption, whereby a crack forming in said solder is influenced to proceed along said interface with a non-planar, interrupted path, thereby lengthening its travel, and preventing failure of said solder joint.

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